

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

() Original () Supplemental () Substitute (V) PCT () Design

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE,
CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE,
CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE,
AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE

of which is described and claimed in:

() the attached specification, or
 () the specification in the application Serial No. _____ filed _____;
 and with amendments through _____ (if applicable), or
 (V) the specification in International Application No. PCT/ JP00/04280, filed June 29, 2000, and as amended on _____ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	11-189053	July 2, 1999	YES
Japan	11-293702	October 15, 1999	YES
Japan	11-308855	October 29, 1999	YES
Japan	11-323979	November 15, 1999	YES
Japan	2000-184467	June 20, 2000	YES

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint John T. Miller, Reg. No. 21,120; Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Jeffrey Nolton, Reg. No. 25,408; Warren M. Cheek, Jr., Reg. No. 33,367; Nils E. Pedersen, Reg. No. 33,145 and Charles R. Watts, Reg. No. 33,142, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., attorneys to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys named herein to accept and follow instructions from Aoyama & Partners as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Send Correspondence to

Direct Telephone Calls to:

WENDEROTH, LIND & PONACK, L.L.P.
2033 K Street, N.W., Suite 800
Washington, DC 20006

WENDEROTH, LIND & PONACK, L.L.P.
Area Code (202) 721-8200

Direct Facsimile Messages to:
Area Code (202) 721-8250

Full Name of First Inventor	FAMILY NAME <u>NARITA</u>	FIRST GIVEN NAME <u>Shoriki</u>	SECOND GIVEN NAME	
Residence & Citizenship	CITY <u>Hirakata-shi, Osaka, Japan</u>	STATE OR COUNTRY <u>JPL</u>	COUNTRY OF CITIZENSHIP <u>Japan</u>	
Post Office Address	ADDRESS <u>45-2-1104, Sakuragaoka-cho, Hirakata-shi, Osaka</u>	CITY <u>573-0018</u>	STATE OR COUNTRY <u>Japan</u>	ZIP CODE
Full Name of Second Inventor	FAMILY NAME <u>TSUBOI</u>	FIRST GIVEN NAME <u>Yasutaka</u>	SECOND GIVEN NAME	
Residence & Citizenship	CITY <u>Hirakata-shi, Osaka, Japan</u>	STATE OR COUNTRY <u>JPL</u>	COUNTRY OF CITIZENSHIP <u>Japan</u>	
Post Office Address	ADDRESS <u>3-17-33-301, Makinosaka, Hirakata-shi, Osaka</u>	CITY <u>573-1146</u>	STATE OR COUNTRY <u>Japan</u>	ZIP CODE
Full Name of Third Inventor	FAMILY NAME <u>IKEYA</u>	FIRST GIVEN NAME <u>Masahiko</u>	SECOND GIVEN NAME	
Residence & Citizenship	CITY <u>Sakai-shi, Osaka, Japan</u>	STATE OR COUNTRY <u>JPL</u>	COUNTRY OF CITIZENSHIP <u>Japan</u>	
Post Office Address	ADDRESS <u>948-2-N102, Kanaoka-cho, Sakai-shi, Osaka</u>	CITY <u>591-8022</u>	STATE OR COUNTRY <u>Japan</u>	ZIP CODE
Full Name of Fourth Inventor	FAMILY NAME <u>MAE</u>	FIRST GIVEN NAME <u>Takaharu</u>	SECOND GIVEN NAME	
Residence & Citizenship	CITY <u>Hirakata-shi, Osaka, Japan</u>	STATE OR COUNTRY <u>JPL</u>	COUNTRY OF CITIZENSHIP <u>Japan</u>	
Post Office Address	ADDRESS <u>305-4, Nagaotanimachi 1-chome, Hirakata-shi, Osaka</u>	CITY <u>573-0164</u>	STATE OR COUNTRY <u>Japan</u>	ZIP CODE

Full Name of Fifth Inventor	FAMILY NAME <u>KANAYAMA</u>	FIRST GIVEN NAME <u>Shinji</u>	SECOND GIVEN NAME
Residence & Citizenship	CITY <u>Kashihara-shi, Nara, Japan</u>	STATE OR COUNTRY <u>JP</u>	COUNTRY OF CITIZENSHIP <u>Japan</u>
Post Office Address	ADDRESS <u>3-11-1-102, Shirakashi-cho, Kashihara-shi, Nara</u>	CITY <u>Japan</u>	STATE OR COUNTRY <u>634-0051</u>
Full Name of Sixth Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE
Full Name of Seventh Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
Residence & Citizenship	CITY	STATE OR COUNTRY	COUNTRY OF CITIZENSHIP
Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor	<u>Shoriki NARITA</u>	Date <u>8.11.2001</u>
2nd Inventor	<u>Yasutaka Tsuboi</u>	Date <u>9.11.2001</u>
3rd Inventor	<u>Masahiko IKEYA</u>	Date <u>9.11.2001</u>
4th Inventor	<u>Takaharu MAE</u>	Date <u>9.11.2001</u>
5th Inventor	<u>Shinji KANAYAMA</u>	Date <u>9.11.2001</u>
6th Inventor		Date _____
7th Inventor		Date _____

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date _____

Applicant Reference Number 534088 Atty Docket No. _____
 Title of Invention BUMP FORMING APPARATUS FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVAL METHOD FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, CHARGE REMOVING UNIT FOR CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE, AND CHARGE APPEARANCE SEMICONDUCTOR SUBSTRATE